

What is claimed is:

1. A method of ablating holes in a material, comprising:

providing a laminated material comprising first and second layers, said first and second
5 layers having different coefficients of thermal expansion, said first layer having within it a hole,
wherein a target region of said second layer in said laminated material is not laminated to said
first layer but is surrounded entirely by laminated regions wherein the first layer is laminated to
the second layer;

providing a laser source producing energy of a wavelength and a power level that can
10 ablate material from said first layer;

changing the temperature of the laminated material so as to place said target region
under tension;

directing said laser source onto said target region and ablating a portion thereof.

2. The method of claim 1, wherein the coefficient of thermal expansion of the first
15 laminate layer is greater than that of the second laminate layer.

3. The method of claim 1, wherein the coefficient of thermal expansion of the second
20 laminate layer is greater than that of the first laminate layer.

4. A method of preparing a laminated material for laser ablation, comprising:
laminating a first layer to a second layer, wherein said first and second layers have
different coefficients of thermal expansion, and wherein said second layer has an interior hole
such that when the laminated substrate is formed, a region of the first layer aligned with said hole
25 is not laminated to the second layer and is surrounded by laminated regions.

5. A laminated material comprising first and second layers, wherein said first and
second layers have different coefficients of thermal expansion, and wherein said second layer has
an interior hole such that a region of the first layer aligned with said hole is not laminated to the
30 second layer and is surrounded by laminated regions.